

Non-Isolated, Phase Dimmable, Buck PFC LED Driver with Digital Reference Control

Check for Samples: [TPS92075](#)

FEATURES

- **Controlled Reference Derived PFC**
- **Integrated Digital Phase-Angle Decoder**
- **Digital 50/60 Hz Synchronization**
- **Phase-Symmetry Balancing**
- **Constant LED current operation**
- **Fast Start-up**
- **Dimming Implemented Via Analog Reference Control**
- **Smooth Dimming Transitions**
- **Overvoltage Protection**
- **Feedback Short-Circuit Protection**
- **Leading and Trailing Edge Dimmer Compatibility**
- **Low BOM Cost and Small PCB Footprint**
- **Patent Pending Digital Architecture**
- **Available in 8-Pin SOIC and 6-Pin TSOT**

DESCRIPTION

The TPS92075 is a hybrid power factor controller (PFC) with a built-in phase dimming decoder. The device analyzes line cycles continuously using an internal, low-power, digital controller for shape and symmetry. The power converter stage generates an analog current reference and uses it to regulate the output current. The device uses control algorithms to manipulate the analog reference. These algorithms optimize dimmer compatibility, power factor and total harmonic distortion (THD).

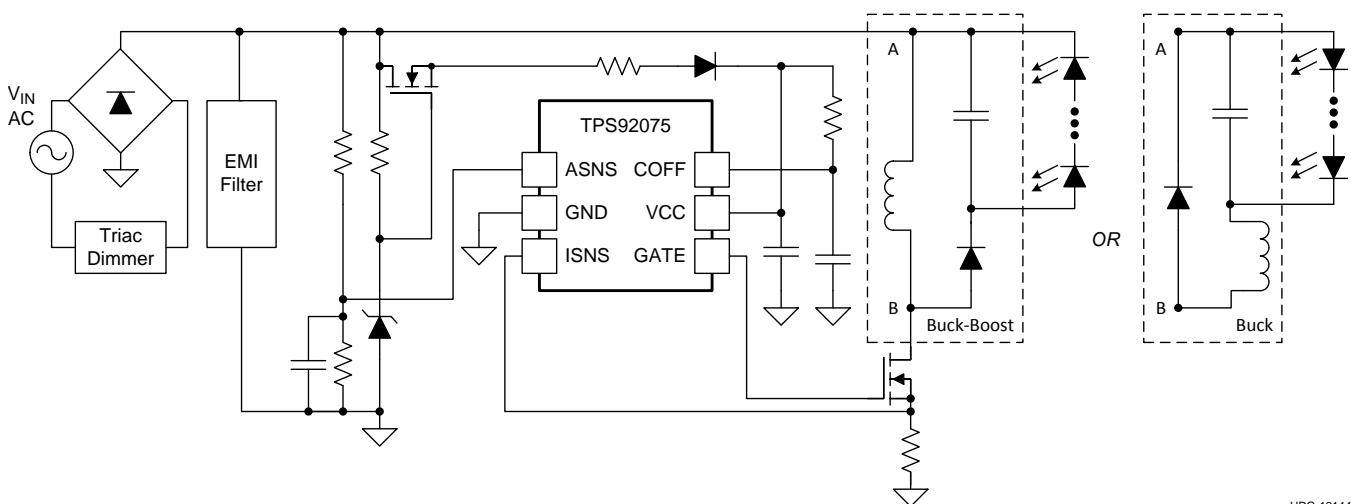
Using a constant off-time control, the solution achieves low component count, high efficiency and inherently provides variation in the switching frequency. This variation creates an emulated spread spectrum effect easing the converters EMI signature and allowing a smaller input filter.

The TPS92075 also includes standard features: current limit, overvoltage protection, thermal shut-down, and VCC undervoltage lockout, all in packages utilizing only 6 pins.

APPLICATIONS

- **Bulb Replacement**
- **Area Lighting**
- **Dimmable and Non-Dimmable LED Lamps**

SIMPLIFIED APPLICATION DIAGRAM



UDG-12144



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

ORDERING INFORMATION⁽¹⁾

| TEMPERATURE RANGE (T _J) | PACKAGE ⁽²⁾ | PINS | ORDERABLE DEVICE NUMBER | TRANSPORT MEDIUM | QUANTITY |
|-------------------------------------|------------------------|------|-------------------------|--------------------|----------|
| -40 to 125°C | SOIC | 8 | TPS92075D | Rail | 95 |
| | | | TPS92075DR | Tape and Reel | 2500 |
| -40 to 125°C | TSOT | 6 | TPS92075DDC | Tape and Mini-Reel | 1000 |
| | | | TPS92075DDCR | Tape and Reel | 3000 |

- (1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.
- (2) Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.

ABSOLUTE MAXIMUM RATINGS⁽¹⁾

All voltages are with respect to GND, $-40^{\circ}\text{C} < T_J = T_A < 125^{\circ}\text{C}$, all currents are positive into and negative out of the specified terminal (unless otherwise noted)

| | | VALUE | | UNIT |
|---|---|--------------------|------|------|
| | | MIN | MAX | |
| Input voltage range | VCC | -0.3 | 22 | V |
| | ASNS, COFF | -0.3 | 6.0 | |
| Bias and ISNS | I _Q bias current (non-switching) | | 2.5 | mA |
| | ISNS ⁽²⁾ to Ground | -0.3 | 2.5 | V |
| Gate | GATE - continuous | -0.3 | 18 | V |
| | GATE - 100 ns | -2.5 | 20.5 | V |
| Continuous power dissipation | | Internally Limited | | |
| Electrostatic discharge | Human Body Model (HBM) | | 2 | kV |
| | Field Induced Charged Device Model (FICDM) | | 750 | V |
| Operating junction temperature, T _J ⁽³⁾ | | | 160 | °C |
| Storage temperature range, T _{stg} | | -65 | 150 | °C |
| Lead temperature, soldering, 10s | | | 260 | °C |

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) ISNS can sustain -2 V for 100 ns without damage.
- (3) Maximum junction temperature is internally limited.

THERMAL INFORMATION

| THERMAL METRIC ⁽¹⁾ | | TPS92075 | | UNITS |
|-------------------------------|---|----------|------------|-------|
| | | SOIC (D) | TSOT (DDC) | |
| | | 8 PINS | 6 PINS | |
| θ _{JA} | Junction-to-ambient thermal resistance ⁽²⁾ | 112.3 | 165.5 | °C/W |
| θ _{JCtop} | Junction-to-case (top) thermal resistance ⁽³⁾ | 58.4 | 28.8 | |
| θ _{JB} | Junction-to-board thermal resistance ⁽⁴⁾ | 52.5 | 24.6 | |
| ψ _{JT} | Junction-to-top characterization parameter ⁽⁵⁾ | 12.5 | 0.3 | |
| ψ _{JB} | Junction-to-board characterization parameter ⁽⁶⁾ | 51.9 | 23.8 | |
| θ _{JCbot} | Junction-to-case (bottom) thermal resistance ⁽⁷⁾ | NA | NA | |

- (1) For more information about traditional and new thermal metrics, see the *IC Package Thermal Metrics* application report, [SPRA953](#).
- (2) The junction-to-ambient thermal resistance under natural convection is obtained in a simulation on a JEDEC-standard, high-K board, as specified in JESD51-7, in an environment described in JESD51-2a.
- (3) The junction-to-case (top) thermal resistance is obtained by simulating a cold plate test on the package top. No specific JEDEC-standard test exists, but a close description can be found in the ANSI SEMI standard G30-88.
- (4) The junction-to-board thermal resistance is obtained by simulating in an environment with a ring cold plate fixture to control the PCB temperature, as described in JESD51-8.
- (5) The junction-to-top characterization parameter, ψ_{JT}, estimates the junction temperature of a device in a real system and is extracted from the simulation data for obtaining θ_{JA}, using a procedure described in JESD51-2a (sections 6 and 7).
- (6) The junction-to-board characterization parameter, ψ_{JB}, estimates the junction temperature of a device in a real system and is extracted from the simulation data for obtaining θ_{JA}, using a procedure described in JESD51-2a (sections 6 and 7).
- (7) The junction-to-case (bottom) thermal resistance is obtained by simulating a cold plate test on the exposed (power) pad. No specific JEDEC standard test exists, but a close description can be found in the ANSI SEMI standard G30-88.

RECOMMENDED OPERATING CONDITIONS⁽¹⁾

Unless otherwise noted, all voltages are with respect to GND, $-40^{\circ}\text{C} < T_J = T_A < 125^{\circ}\text{C}$.

| | MIN | TYP | MAX | UNIT |
|--------------------------------|-----|-----|-----|--------------------|
| Supply input voltage range VCC | | 11 | 18 | V |
| Operating junction temperature | -40 | | 125 | $^{\circ}\text{C}$ |

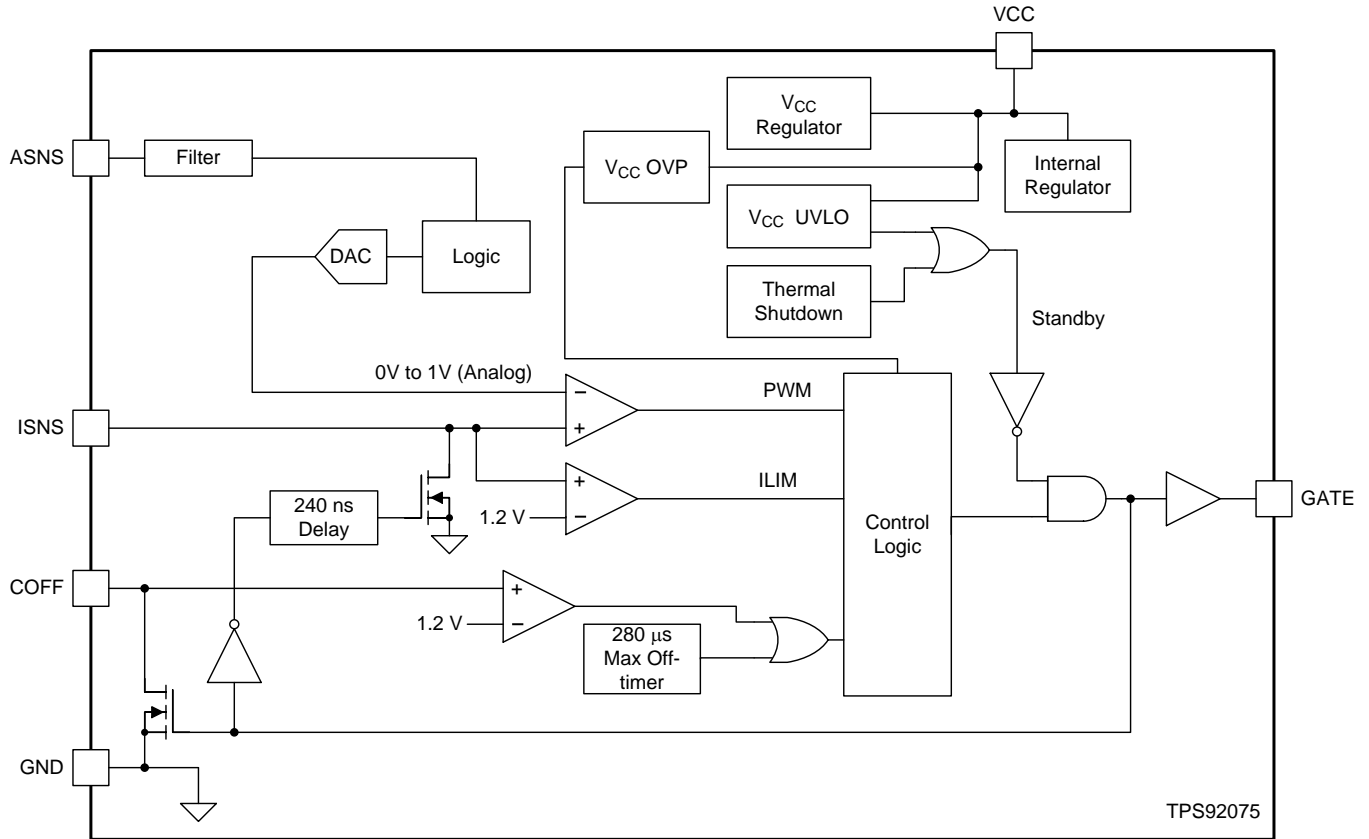
(1) Operating Ratings are conditions under which operation of the device is specified and do not imply assured performance limits. For specified performance limits and associated test conditions, see the Electrical Characteristics table.

ELECTRICAL CHARACTERISTICS

Unless otherwise specified $-40^{\circ}\text{C} \leq T_J = T_A \leq 125^{\circ}\text{C}$, $V_{\text{CC}} = 14\text{ V}$, $C_{\text{VCC}} = 10\ \mu\text{F}$, $C_{\text{GATE}} = 2.2\ \text{nF}$

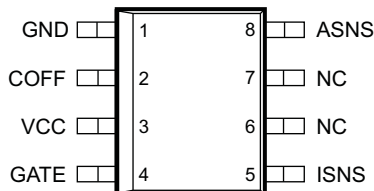
| PARAMETER | | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|-----------------------------------|------------------------------------|---|-------|-------|-------|--------------------|
| SUPPLY VOLTAGE INPUT (VCC) | | | | | | |
| I_Q | VCC quiescent current | Not switching | | 1.3 | 2.5 | mA |
| I_{Q_SD} | VCC low power mode current | $V_{\text{CC}} < V_{\text{CC(UVLO)}}$ | | 120 | 250 | μA |
| V_{VCC} | Input range | $V_{\text{CC}} \leq V_{\text{CC(OVP)}}$ | | | 18 | V |
| $V_{\text{CC(OVP)}}$ | Overshoot protection threshold | $V_{\text{CC}} > V_{\text{CC(OVP)}}$ | 18.0 | | 20.0 | V |
| $V_{\text{CC(UVLO)}}$ | VCC UVLO threshold | VCC rising | | 9.8 | 10.5 | V |
| | | VCC falling | 5.75 | 6.40 | | V |
| $V_{\text{CC(HYS)}}$ | VCC UVLO hysteresis | | | 3.3 | | V |
| ANGLE DEMODULATION | | | | | | |
| $ASNS_{\text{TH-Hi}}$ | Angle detect rising threshold | | 0.9 | 1.0 | 1.1 | V |
| $ASNS_{\text{TH-Low}}$ | Angle detect falling threshold | | 0.465 | 0.500 | 0.540 | V |
| OFF-TIME CONTROL | | | | | | |
| V_{COFF} | OFF capacitor threshold | | 1.14 | 1.20 | 1.285 | V |
| R_{COFF} | OFF capacitor pull-down resistance | | | 33 | 60 | Ω |
| $t_{\text{OFF-max}}$ | Maximum off-time | | | 280 | | μs |
| GATE DRIVER OUTPUT (GATE) | | | | | | |
| $R_{\text{GATE(H)}}$ | Gate sourcing resistance | | | 3 | 8 | Ω |
| $R_{\text{GATE(L)}}$ | Gate sinking resistance | | | 3 | 8 | Ω |
| CURRENT SENSE | | | | | | |
| V_{ISNS} | Average ISNS limit threshold | DAC: 63/127 | 445 | 500 | 555 | mV |
| V_{CL} | Current Limit | | | 1.2 | | V |
| t_{ISNS} | Leading edge blanking | | | 240 | | ns |
| | Current limit reset delay | | | 280 | | μs |
| | ISNS limit to GATE delay | | | 33 | | ns |
| $t_{\text{COFF_DLY}}$ | OFF capacitor limit to GATE delay | | | 33 | | ns |
| THERMAL SHUTDOWN | | | | | | |
| T_{SD} | Thermal limit threshold | | | 160 | | $^{\circ}\text{C}$ |
| T_{HYS} | Thermal limit hysteresis | | | 20 | | $^{\circ}\text{C}$ |

DEVICE INFORMATION
FUNCTIONAL BLOCK DIAGRAM

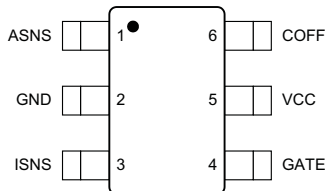


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**SOIC (D) PACKAGE
8 PINS
(TOP VIEW)**



**TSOT (DDC) PACKAGE
6 PINS
(TOP VIEW)**



PIN DESCRIPTIONS

| NAME | PIN NUMBERS | | I/O | DESCRIPTION |
|------|-------------|------------|-----|--|
| | SIOC (D) | TSOT (DDC) | | |
| ASNS | 8 | 1 | I | The phase of the TRIAC is detected through this pin and is then fed to the digital decoder. Sensing thresholds are 1V rising and 0.5V falling – nominal. |
| COFF | 2 | 6 | I | Used to set the converter constant off-time. A current and capacitor connected from the output to this pin sets the constant off-time of the switching controller. |
| GATE | 4 | 4 | O | Power MOSFET driver pin. This output provides the gate drive for the power switching MOSFET. |
| GND | 1 | 2 | — | Circuit ground connection |
| ISNS | 5 | 3 | I | LED current sense pin. Connect a resistor from main switching MOSFET source to GND to set the maximum switching cycle LED current. Connect ISNS to the switching FET source. |
| VCC | 3 | 5 | — | Input voltage pin. This pin provides the power for the internal control circuitry and gate driver. VCC undervoltage lockout has been implemented with a wide range: 10V rising, 6V falling to ensure operation with start-up methods that allow elimination of the linear pass device. This includes using a coupled inductor with resistive start-up. |

TYPICAL CHARACTERISTICS

Unless otherwise stated, $-40^{\circ}\text{C} \leq T_A = T_J \leq 125^{\circ}\text{C}$, $V_{CC} = 14\text{ V}$, $C_{VCC} = 10\ \mu\text{F}$, $C_{GATE} = 2.2\ \text{nF}$

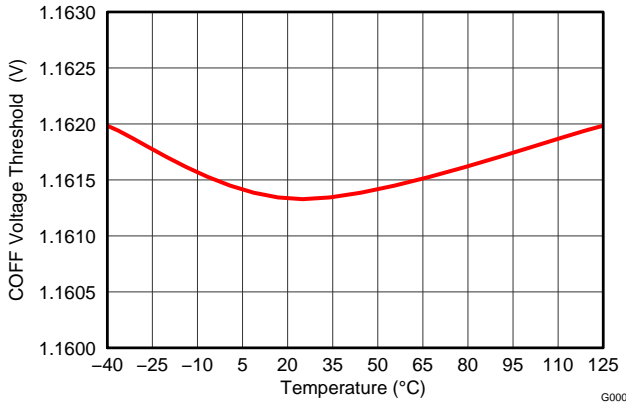


Figure 1. COFF Threshold Voltage vs Temperature

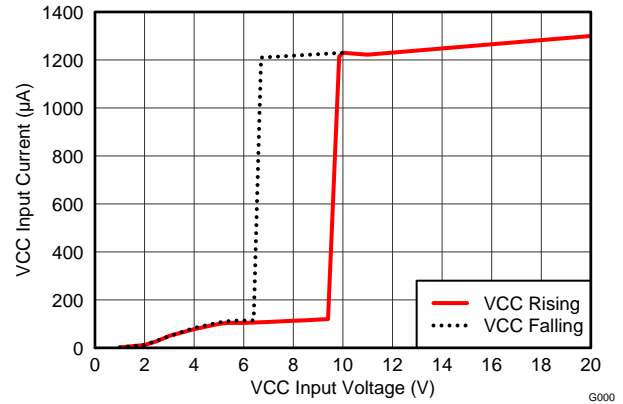


Figure 2. VCC Input Current vs Vcc Input Voltage

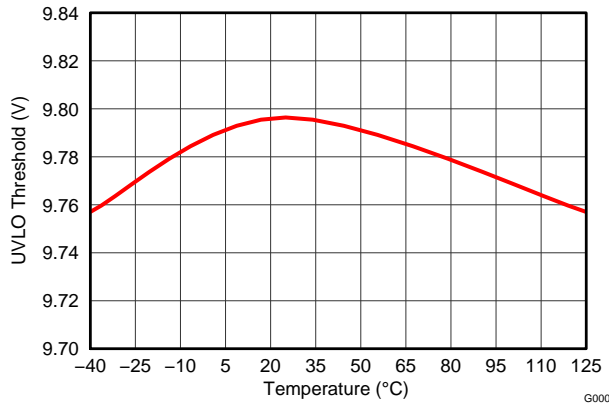


Figure 3. Input Voltage (UVLO Rising) vs Junction Temperature

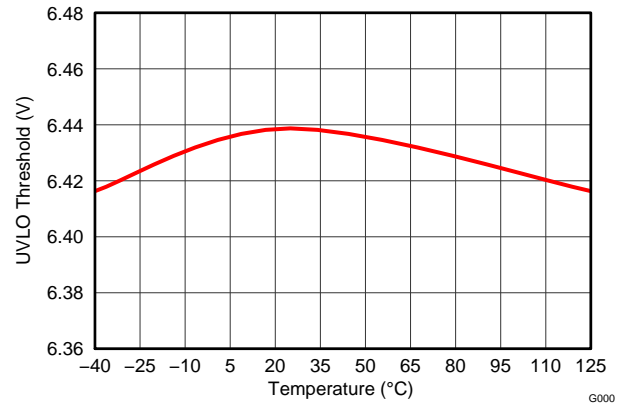


Figure 4. Input Voltage (UVLO Falling) vs Junction Temperature

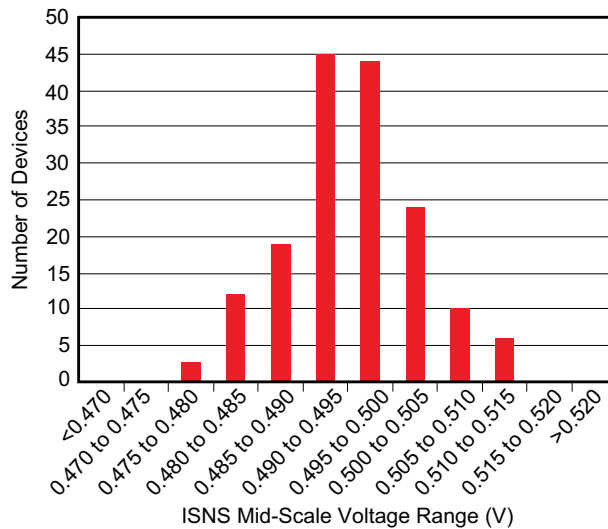


Figure 5. ISNS 0.5V Threshold Distribution

Initial Start-Up

The TPS92075 is designed to achieve instant turn-on using an external linear regulator circuit. The start-up sequence is internally controlled by a V_{CC} under-voltage lockout (UVLO) circuit. Sufficient headroom has been incorporated to support the use of an auxiliary winding with start-up linear, resistive or coupled capacitor start-up methods.

VCC Bias Supply

The TPS92075 can be configured to use a linear regulator with or without the use of an auxiliary winding. Using a linear regulator to provide V_{CC} incurs more losses than an auxiliary winding, but has several advantages:

- allows the use of inexpensive off-the-shelf inductors as the main magnetic
- speeds start-up time under deep dimming conditions
- can reduce the size of the required VCC capacitor
- the extra current draw when dimming can improve dimming compatibility

Another consideration when selecting a bias method involves the OVP configuration. Because the feature is enabled via the VCC pin, an auxiliary winding provides the simplest implementation of output over-voltage protection.

A typical start-up sequence begins with V_{CC} input voltage below the UVLO threshold and the device operating in low-power, shut-down mode. The V_{CC} input voltage increases to the UVLO threshold of 9.8V typical. At this point all of the device features are enabled. The device loads the initial start-up value as the output reference and switching begins. The device operates until the V_{CC} level falls below the $V_{CC(UVLO)}$ falling threshold. (6.4V typical) When V_{CC} is below this threshold, the device enters low-power shut-down mode.

Angle Sense Operation

The ASNS (angle sense) pin is the only input to the digital controller. The time between the rising edge and the falling edge of the signal determines converter functions. The pin incorporates internal analog and digital filtering so that any transition that remains beyond the threshold for more than approximately 150 μ s will cause the device to record a change-of-state.

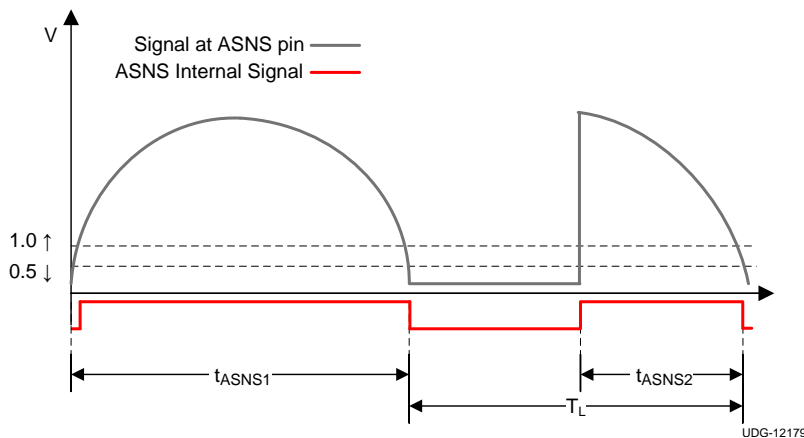


Figure 8. Angle Sense Operation

Controller

Basic Operation and Modes

The controller continuously monitors the line cycle period and the present conduction angle length to determine the state of operation and configure other control features. Control algorithms use a normalized line period of 256 samples from ASNS fall to ASNS fall and a normalized converter reference control of 127 levels over a range of 0V to 1V .

The four main controller states are:

- Start-up
- Non-Dimming
- Dimming
- ASNS signal lost

With the exception of start-up, the controller can enter any of the states at any time as conditions demand.

The two primary modes of controlling the converter reference are:

- DC mode
- Ramp mode

During active dimming, a DC control reference increases or decreases depending on the input AC duty cycle derived from the ASNS signal. The relationship follows the algorithm: (ASNS Length + Fixed Offset) = Output Set point. When the conduction angle is long enough, the converter reference is changed to a triangular ramp to achieve a high power factor. The ramp is generated gradually over several cycles ensuring the implementation is undetectable. The controller maintains the ramp between the rising and falling ASNS signals.

The controller also sets DC reference levels during start-up and when the ASNS signal is lost. Active states in the controller and controlled ranges are shown in [Table 1](#).

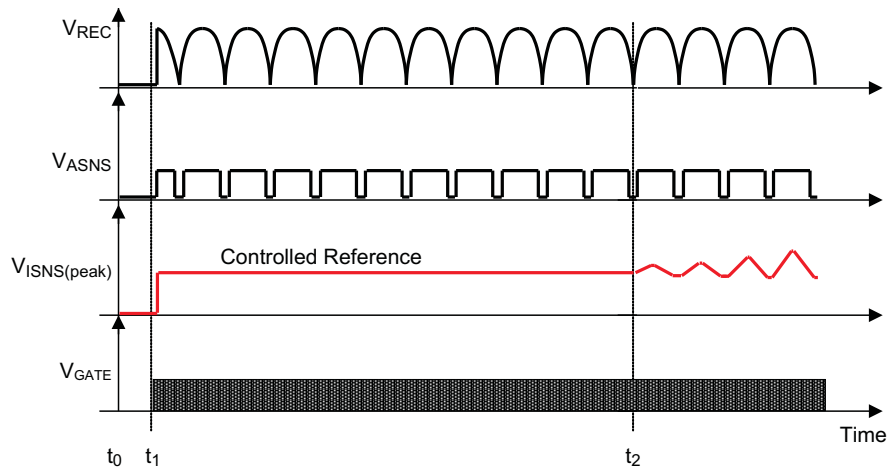
Table 1. Control States and Controlled Reference Values

| MODE | LINE DUTY CYCLE | CONTROLLED REFERENCE VALUE |
|-------------|---------------------------|---------------------------------|
| | | (value / 127) X 1V = reference |
| Start-up | Any | 50 |
| Non-Dimming | > 70%, typical average | 55 |
| | > 70%, typical ramp range | 22 to 127 |
| Dimming | ≤ 70% | 35 to 63 |
| No ASNS | Any | 42 |

Initial Start-up

Line Synchronization

When the device reaches the turn-on UVLO threshold, the output current reference resets to 0.393V (50/127) and switching begins. The controller samples the line for approximately 80 ms (t_1 to t_2 , Figure 9) to determine the line frequency and establish the present state of operation. After determining the line frequency, the controller uses the information to calibrate the internal oscillator. The controller supports line frequencies from 45Hz to 65Hz. After determining frequency and duty cycle, the controller enters the appropriate control state.

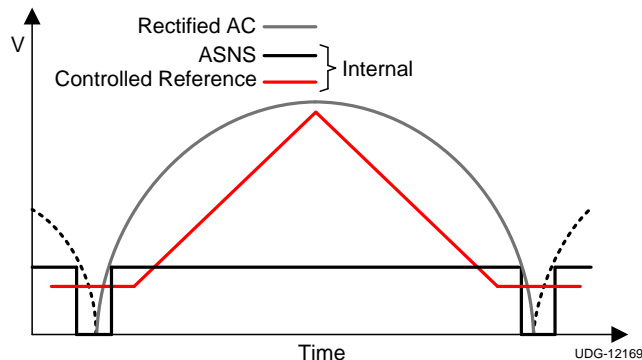


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Figure 9. Line Synchronization

Non-Dimming Ramp Mode

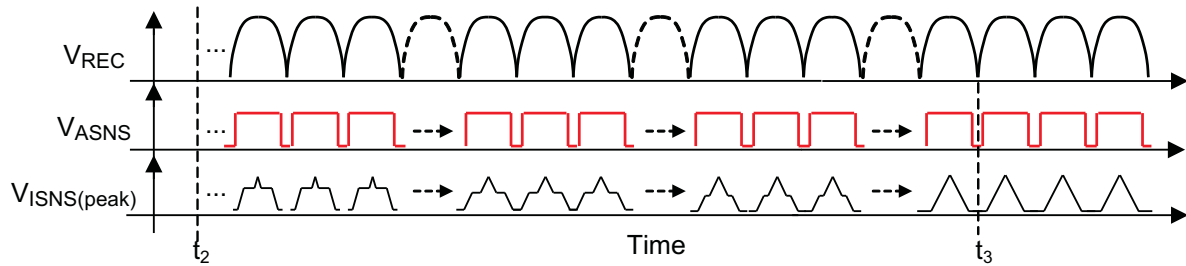
When the conduction angle is greater than 70%, the controller begins to create a triangular ramp that is synchronized to the line and is centered between rising and falling edges of the ASNS signal as shown in Figure 10. The triangular shape is much easier to generate than a sine wave while maintaining a high power factor and low THD. The edges of the ramp do not decrease completely to zero to ensure compatibility with TRIAC dimmers that can provide conduction angles approaching 100%.



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Figure 10. Controlled Reference Output, Non-dimming

When changing between dimming mode and non-dimming mode, the ramp is created over 127 line cycles (see Figure 11) or approximately 1 second (t_2 to $t_3 \approx 1$ second). Because the output level before and after the change is very similar and the change very gradual, it is impossible for the user to perceive a change in output level. The ramp morphs from a DC level to a ramp using a method that further ensures transparency to the user. Ramp transition occurs during construction and deconstruction of the ramp and is reversed if the conduction angle changes sufficiently during the change process. A hysteresis in angle length is also built in to the change-to-ramp-mode and change-from-ramp-mode transition.



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Figure 11. Transition Stages of the Controlled Reference

Dimming Mode

When the conduction angle is reduced below the 70% threshold the output is controlled with a DC reference level based on: $(\text{angle sense rise to fall length count}) / 2 + 35, \leq 63$. The control level clamps at both the high and low end of the range to increase TRIAC dimmer compatibility. Rather than adding passive (heat generating) hold current or implementing other means to draw sufficient current from the TRIAC dimmer to maintain optimal operation, the TPS92075 implements a translation that shifts output demand higher, lower in the dimming range. The effect is that more current is drawn at low angles, eliminating the need for hold circuitry. A net reduction in light output occurs because of the energy transfer relation. As the phase-dimmer conduction decreases, the time during which the converter can provide output power during each cycle decreases, and a reduction in light output follows.

Triac Asymmetry Balancing

Triacs are two silicon-controlled rectifiers (SCRs) configured so that one device conducts current in the positive AC cycle and the other device conducts current in the negative AC cycle. It is common for the devices to have different trigger levels and this leads to differences in conduction angle for each of the positive and negative AC cycles. The amount of variation between each cycle varies greatly between dimmer brands, makes and models. In all single stage TRIAC compatible dimming solutions, the ability of the converter to provide output power depends on the length of the conduction time. If the output current demand remains constant during each cycle and if there is a difference in TRIAC conduction angles, the result is a difference in light output for each cycle.

The TPS92075 incorporates a balancing algorithm to reduce the difference in LED current (and light output) between cycles that have a conduction angle difference greater than 20%.

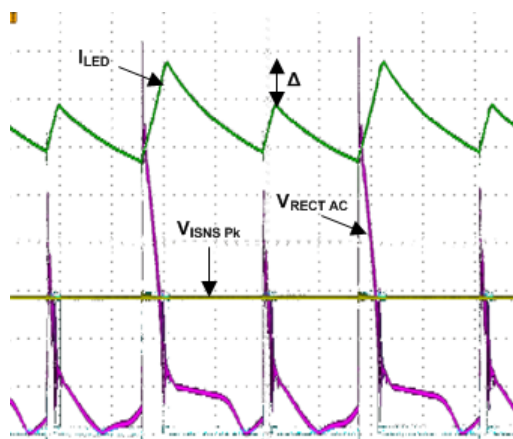


Figure 12. LED current variation, Constant Reference

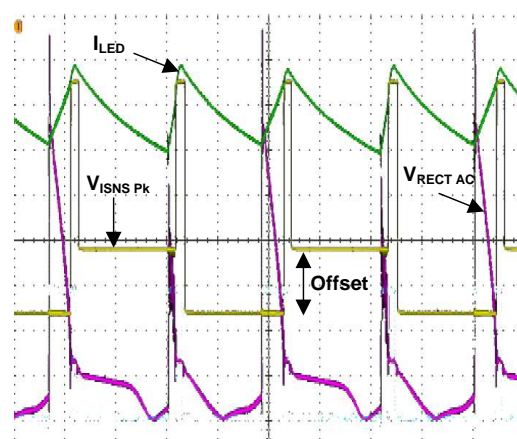


Figure 13. LED current variation, TPS92075 with Balancing

When the difference in conduction becomes greater than 20%, the controller begins to adjust the controller reference line-cycle by line-cycle to balance the energy provided to the LEDs. In this example the difference in conduction angles is 800 μs and flicker was visible with the constant reference (Figure 12). With the TPS92075 balancing feature the peaks in the LED current have been equalized and flicker cannot be seen (Figure 13).

Lossless or 'Active' Hold

When used in the buck configuration, the converter enters a drop-out condition each cycle as the input AC line drops below the LED stack voltage. When this occurs, a resonance in the input filter can be excited causing a ring in the input current at the end of the conduction cycle. This can lead to output flicker if not controlled. One method of eliminating this is to modify the control method to send the energy that would otherwise affect the ringing to the output. To do this, the controller increases the output set-point at the end of each cycle after the ASNS fall ($< 0.5\text{ V}$) signal is received. The increase in set point can be seen in [Figure 14](#).

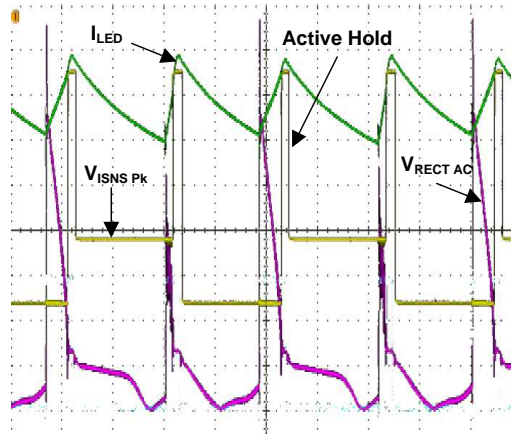


Figure 14. TPS92075 Reference Control - Active Hold

Another benefit of the active hold is that a low impedance path is created to the LED stack. This ensures the current demand is as high as possible for as long as possible before the converter fully enters drop-out.

Active Hold, ASNS, and Buck-Boost Topology

When using the converter in a buck-boost configuration attention must be given to the configuration of the ASNS signal to ensure there is some added delay in the signal crossing the 0.5V threshold. Because the converter can continue to provide energy to the output below the LED stack voltage, it is best to configure the ASNS signal to fall when the rectified AC signal is as close to zero as possible.

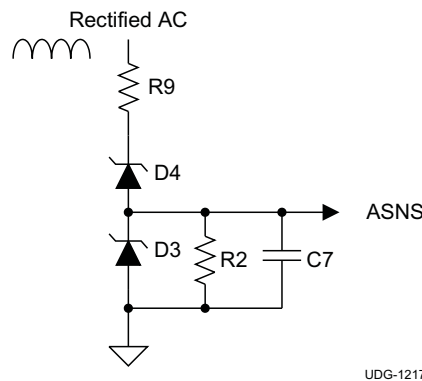


Figure 15. Buck-Boost Angle Sense Circuit

This can be implemented by adding an additional zener and capacitor on the ASNS pin. Capacitance between 2200 pF and 4700 pF provides a good balance between allowing the ASNS signal to fall below 0.5V and extending the ASNS time. The D4 zener allows the ASNS signal to be widened further. This component can be the same type of zener selected for the input voltage linear supply, in many prototyping examples a 15V zener diode is used. The buck-boost configuration tends to provide greater dimmer compatibility because of its ability to continue to draw power below the LED stack. This increases the time the converter can provide output current and increases the light output at a given dimmer setting. A higher light output for a given dimmer setting is an important control technique which increases the probability that the design will remain flicker-free over its lifetime and range of installations. This trade-off between dimming ratio, dimmer compatibility and component count make the components a desirable addition.

Loss of Angle Sense

When using a dimmer that can control the phase angle to very short conduction times (< 250 μ s), the ASNS signal may become so narrow that the controller cannot determine its length. When this occurs the controller simply sets the reference to a default value 0.33V (42/127) and waits for the ASNS signal to return.

A simplified version of the TPS92075 circuit can be implemented by grounding the ASNS signal if minimum component count and size are essential design criteria. In this configuration balancing, ramp mode and active hold are not implemented. The output is controlled with a default, static reference of 0.394V (50/127). If used in conjunction with an on-time clamp, good dimming and power factors (>0.9) can still be achieved.

Thermal Shutdown

The TPS92075 includes thermal shutdown protection. If the die temperature reaches approximately 160°C the device stops switching (GATE pin low). When the die temperature cools to approximately 140°C, the device resumes normal operation.

If thermal fold back is desired at levels below the IC thermal shut down, application circuits have been created to implement this feature. The simplest of these is the addition of a thermistor in the off-time circuitry.

Thermal Foldback

To implement thermal foldback, adjust the resistance of an existing circuit resistor with the use of an NTC (negative temperature coefficient) thermistor.

For example, a resistor combination creating a dominant effect when the thermistor reaches the desired temperature and resistance can be incorporated by paralleling a thermistor and another resistor with R10 (Figure 17). This circuit option creates a shorter on-time as the temperature increases, reducing the output current. The use of a thermistor in these types of circuit implementations is simple and saves costly added circuitry and additional device pins.

Overvoltage Protection (OVP)

The implementation of overvoltage protection is simple and built-in if using a two-coil magnetic (coupled inductor) to derive V_{CC} . If the LED string is opened the auxiliary V_{CC} rises and reaches the $V_{CC(OVP)}$ trip point. This action disables and grounds the gate pin, preventing the converter from switching. The converter remains disabled until V_{CC} drops 0.5V after a 1 second time-out. If an inductor is used, implement other discrete circuits to disable the converter.

Output Bulk Capacitor

The required output bulk capacitor, C_{BULK} , stores energy during the input voltage zero crossing interval and limits twice the line frequency ripple component flowing through the LEDs. [Equation 1](#) describes the calculation of the of output capacitor value.

$$C_{BULK} \geq \frac{P_{IN}}{4\pi \times f_L \times R_{LED} \times V_{LED} \times I_{LED(ripple)}}$$

where

- R_{LED} is the dynamic resistance of LED string
- $I_{LED(ripple)}$ is the peak to peak LED ripple current
- and f_L is line frequency

(1)

R_{LED} is found by computing the difference in LED forward voltage divided by the difference in LED current for a given LED using the manufacturer's V_F vs. I_F curve. For a rough initial estimate a typical value of 0.25 Ω per LED can be used. More detail can be found in [Application Note 1656](#).

In typical applications, the solution size becomes a limiting factor and dictates the maximum dimensions of the bulk capacitor. When selecting an electrolytic capacitor, manufacturer recommended de-rating factors should be applied based on the worst case capacitor ripple current, output voltage and operating temperature to achieve the desired operating lifetime. It should also be a consideration to provide a minimum load at the output of the driver to discharge the capacitor after the power is switched off or during LED open circuit failures.

Design Guidelines

This TPS92075 application design requires the selection of components for the power conversion stage and angle sensing. Output inductor, sense resistor and switching frequency are the key aspects of the power stage design. Another important consideration is the inclusion of an on-time clamp. The combination of the line voltage going to zero each cycle and the hysteretic control method can lead to large increases in current draw at the start and end of each cycle. The components required for the on-time clamp are very inexpensive and return results that make their inclusion a common choice for LED driver designers. This simplified design procedure assumes the use of an on-time clamp in the design.

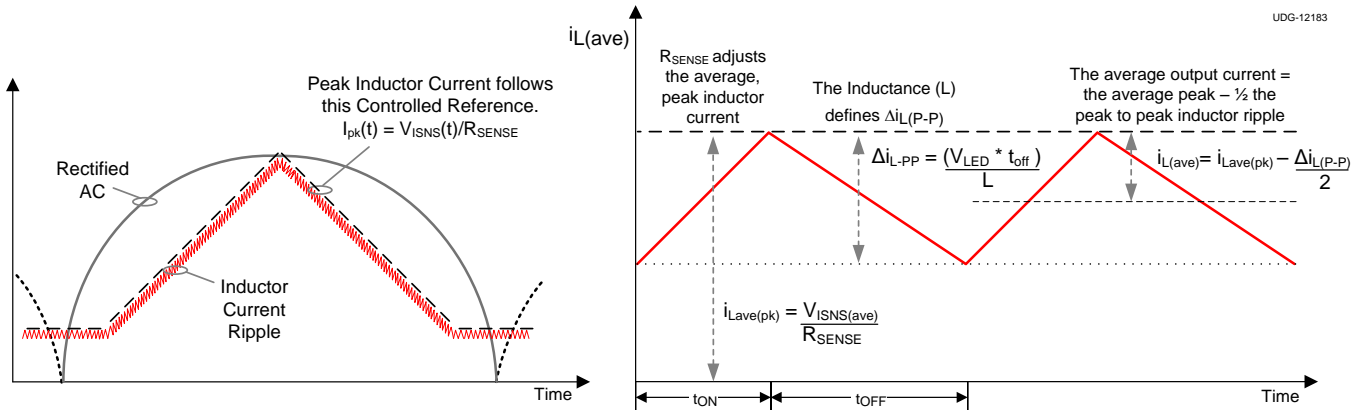


Figure 16. TPS92075 Output Current Control

The mode of operation that determines average continuous output current is non-dimming, during which the reference is a triangular waveform.

The device uses the controller reference every switching cycle to set the peak current through the main switch and sense resistor. The average value of this reference and the inductor ripple current can be used to calculate the average output current. Another consideration is the length of time the converter is providing power to the LEDs. A conversion factor (CF) that accounts for a lower level of power conversion at the ends of each cycle is used to provide a more accurate sense resistor value. The lower level of power conversion in these areas also helps to increase the power factor. For the R_{SENSE} calculation use $V_{ISNS(ave)} = 0.433V$ (55/127). The CF calculation involves computing the normalized time length of the angle sense pulse using a formula shown in Equation 3. Simplified design expressions are provided below. For a more comprehensive approach refer to the TPS92075 Design Spreadsheet.

To calculate R_{SENSE} , use Equation 2.

$$R_{SENSE} = \left(\frac{V_{ISNS(ave)}}{I_{LED} + \frac{\Delta i_{L(P-P)}}{2}} \right) \times CF \quad (2)$$

To calculate the conversion factor, use Equation 3.

$$CF = 1 - \left(\frac{\sin^{-1} \left(\frac{V_{LED}}{\sqrt{2} \times V_{RMS}} \right)}{90} \times \frac{3}{2} \right) \quad (3)$$

To calculate inductance ripple, use Equation 4.

$$\Delta i_{L(P-P)} = \left(\frac{V_{LED} \times t_{OFF}}{L} \right) \quad (4)$$

To calculate the constant off-time, use Equation 5

$$t_{\text{OFF}} = \left(\ln \left(- \left(\frac{1.2}{V_{\text{VCC}}} - 1 \right) \right) \right) \times (-C_{\text{TOFF}} \times R_{\text{COFF}}) \quad (5)$$

To calculate the average switching frequency, use [Equation 6](#).

$$f_{\text{SW}} = \left(\frac{1}{t_{\text{OFF}} + (t_{\text{OFF}} \times \text{CF})} \right) \quad (6)$$

On-Time Clamp

The use of an on-time clamp ([Figure 17](#)) provides a soft-start and soft-stop action to the conversion each line cycle. It also adds a means to control the energy in these conversion areas to optimize dimming performance. For example, cutting the energy conversion in these areas in half maintains strong current pull through these critical TRIAC regions, but is not high enough to excite circuit resonances.

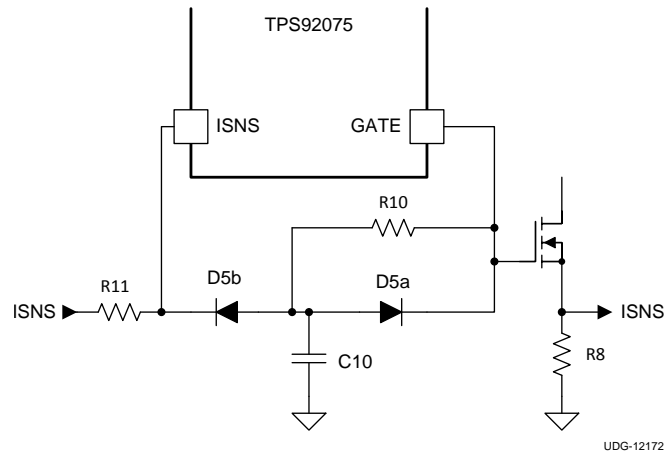


Figure 17. On-time Clamp Circuitry

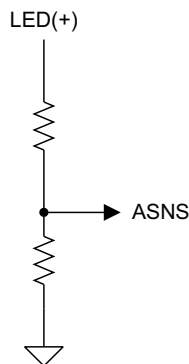
The circuit uses the gate drive output to generate a ramp. The ramp increases at a rate to reach the current sense trip point at the desired maximum conduction time. The gate signal, resistor R10 and capacitor C10 create the ramp. Diode D5b resets the ramp for each switching cycle. Resistor R11 provides an impedance so this signal can override ISNS.

In the regions at the start and end of a line cycle the current sense reference is controlled to 0.173V (22/127). To select an R-C to reach this point in the desired time use [Equation 7](#). A good starting estimate for the maximum on-time clamp is $\sim t_{\text{OFF}}/2$. For example, choosing 33 nF as the value of capacitor C10, and assuming $V_{\text{GATE}} \approx V_{\text{CC}}$, R10 ($R_{\text{ton(max)}}$) is calculated in [Equation 7](#).

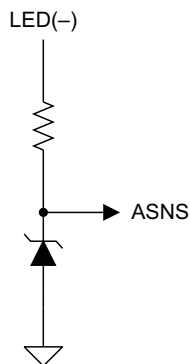
$$R_{\text{ton(max)}} = \frac{t_{\text{OFF}}}{2 \times \left[\ln \left(- \left(\frac{0.173}{V_{\text{GATE}}} - 1 \right) \right) \right] \times -C_{\text{ton(max)}}} \quad (7)$$

Angle Sense Circuitry and Minimum ASNS Signal Length

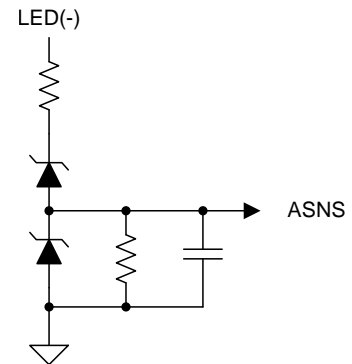
If implementing a buck converter, select the divider so the falling 0.5V ASNS threshold is reached when the rectified AC voltage is at the LED stack voltage. For example, if the LED stack is 20V and the top resistor is 400 k Ω , the bottom resistor should be 10.25 k Ω to provide a falling ASNS signal at 0.5V when the rectified AC reaches 20V. A 20V ASNS falling signal will mean a 40V ASNS rising threshold because of the 2:1 hysteresis. This will provide an ASNS signal length of ~7.4 ms, adequate to activate the ramp mode when not connected to a dimmer. This buck configuration and ASNS divider will activate the hold feature each time the rectified AC reaches the LED stack voltage. This method is shown in [Figure 18](#). Regardless of the ASNS connection method used, the divider must ensure an adequate angle sense length ($t_{ASNS} > 5.9$ ms) when non-dimming to activate the creation of the ramp if this is desired. For example, if a straight resistor divider ([Figure 18](#)) is implemented and the design LED stack is more than 42V, the ASNS conduction time may not be adequate to activate the use of the ramp reference.



UDG-12173

Figure 18. Angle Sense for Low Voltage Buck Applications


UDG-12174

Figure 19. Angle Sense for Buck Applications up to 65V


UDG-12175

Figure 20. Angle Sense for Buck-Boost Applications

For LED stack voltages between 3V and 65V, use an alternate method that senses from LED(-). Because LED(-) reaches ground each line cycle, the absolute ASNS comparison limits of 0.5V and 1V can be used, providing extra conduction time for the ASNS signal as shown in [Figure 19](#). Beyond a ~65V LED stack, alternate ASNS methods utilizing a bridge tap can be used. For buck-boost applications, implement the circuit shown in [Figure 20](#).

A capacitor on the ASNS pin may be required, depending on operating conditions.

EMI Filtering: AC versus DC side of the rectifier bridge

The TPS92075 requires a minimal amount of EMI filtering to pass conducted and radiated emissions levels to comply with agency requirements. Applications have been tested with the filter on the AC or DC side of the diode bridge and have obtained passing results. The use of an R-C snubber to damp filter resonances and optimize TRIAC compatibility is strongly recommended. The EMI filter design involves optimizing several factors and design considerations, including:

- the use of 'X' versus non-X rated filter capacitors
- the use of ceramic versus film capacitors
- component rating requirements when on the AC or DC side of the diode bridge
- filtering on the AC or DC side of the bridge and the effect on the TRIAC firing angle and dimming range
- snubber time constant and position in the design schematic
- filter design choices and audible noise

Application Circuits

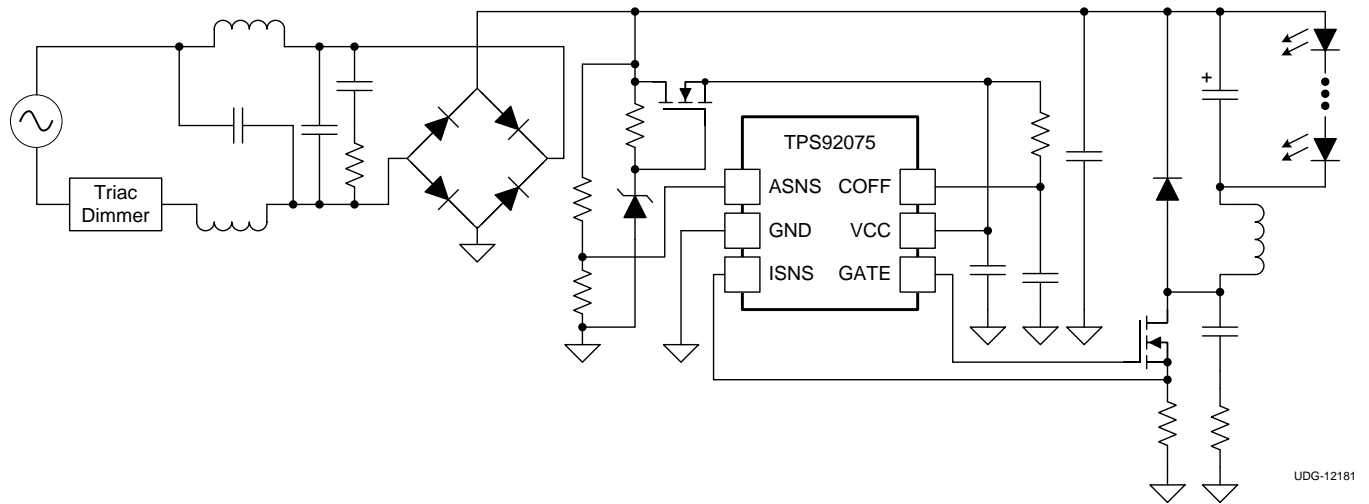


Figure 21. TPS92075 Application Circuit for Buck Topology with AC Side Filter

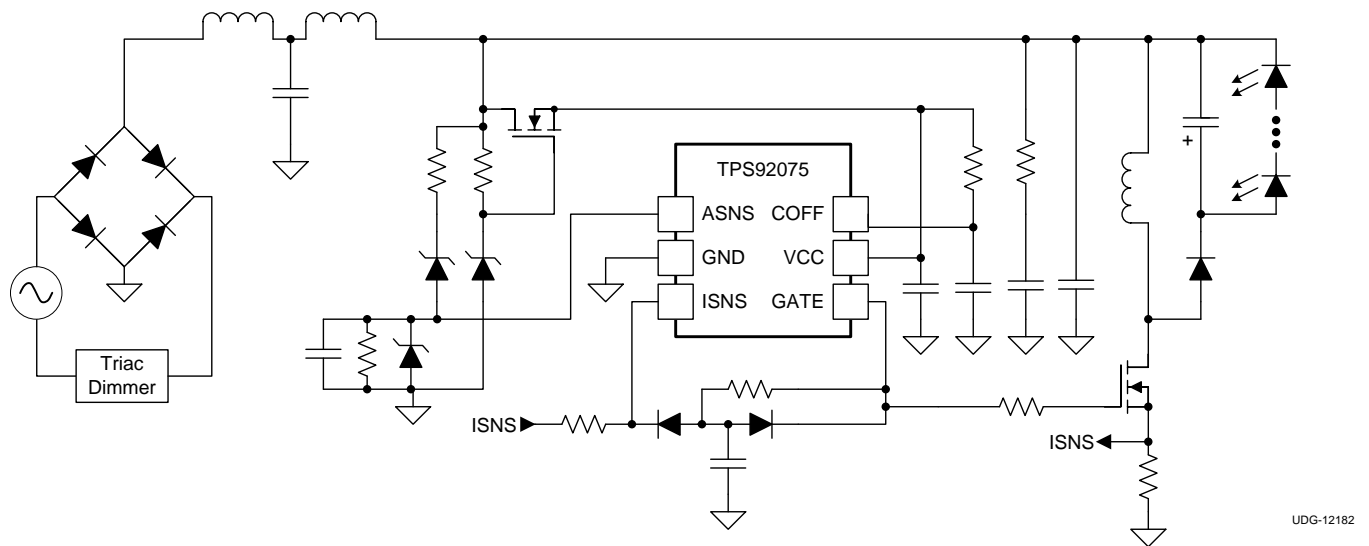
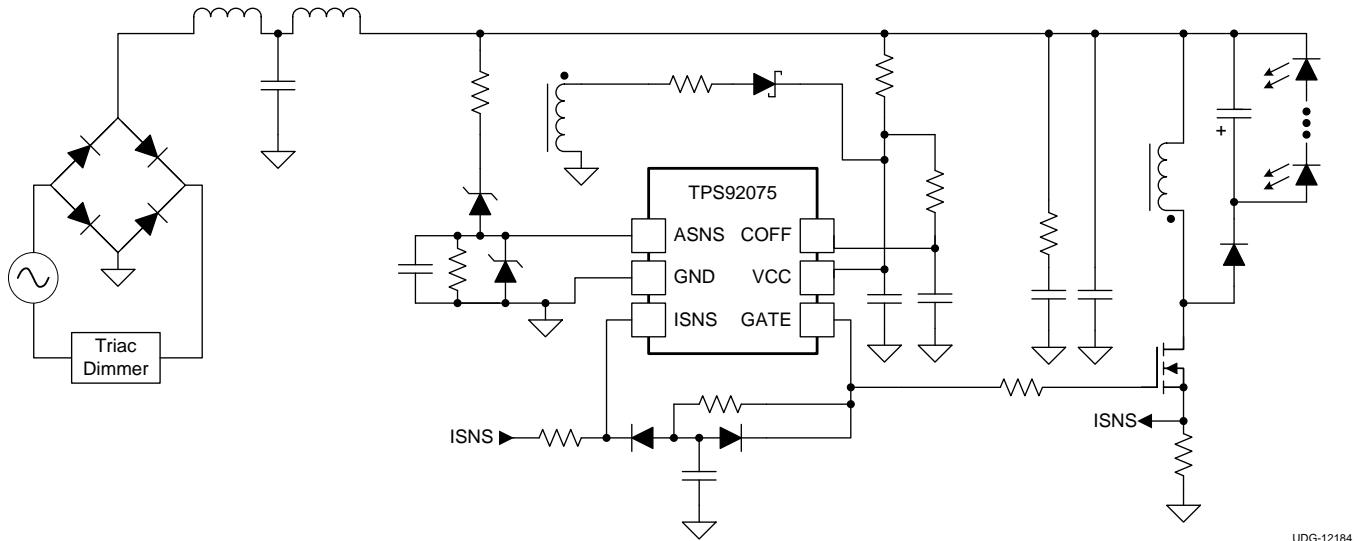


Figure 22. TPS92075 Application Circuit for Buck-Boost Topology with DC Side Filter



UDG-12184

Figure 23. TPS92075 Application Circuit for Buck-Boost with Resistive Start-up and AUX Supply

REVISION HISTORY

Changes from Revision A (JANUARY 2013) to Revision B **Page**

- Changed TSOT package availability status in FEATURES section 1
-

Changes from Original (DECEMBER 2012) to Revision A **Page**

- Changed title of [Figure 7](#) 8
 - Changed [Figure 17](#) to correct resistor position 16
 - Changed [Figure 22](#) to correct resistor position 18
 - Changed [Figure 23](#) to correct resistor position 19
-

PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|-------------------|---------------|--------------|-----------------|------|-------------|-------------------------|-------------------------|----------------------|--------------|-------------------------|-------------------------|
| TPS92075D/NOPB | ACTIVE | SOIC | D | 8 | 95 | Green (RoHS & no Sb/Br) | CU SN | Level-1-260C-UNLIM | -40 to 125 | T92075 | Samples |
| TPS92075DDC/NOPB | ACTIVE | SOT-23-THIN | DDC | 6 | 1000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | SN8B | Samples |
| TPS92075DDCR/NOPB | ACTIVE | SOT-23-THIN | DDC | 6 | 3000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | SN8B | Samples |
| TPS92075DR/NOPB | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU SN | Level-1-260C-UNLIM | -40 to 125 | T92075 | Samples |

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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TAPE AND REEL INFORMATION

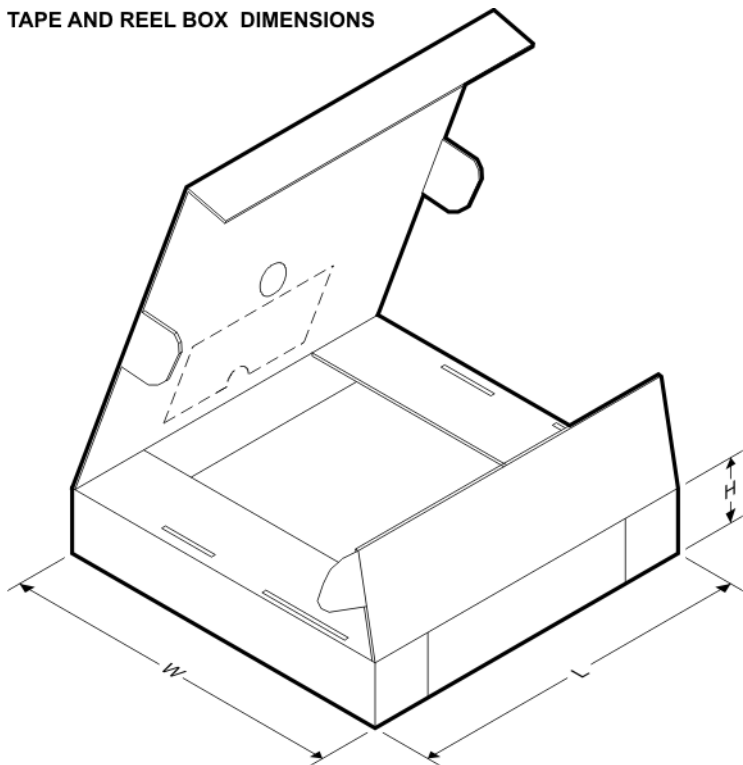


QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|-------------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| TPS92075DDC/NOPB | SOT-23-THIN | DDC | 6 | 1000 | 178.0 | 8.4 | 3.2 | 3.2 | 1.4 | 4.0 | 8.0 | Q3 |
| TPS92075DDCR/NOPB | SOT-23-THIN | DDC | 6 | 3000 | 178.0 | 8.4 | 3.2 | 3.2 | 1.4 | 4.0 | 8.0 | Q3 |
| TPS92075DR/NOPB | SOIC | D | 8 | 2500 | 330.0 | 12.4 | 6.5 | 5.4 | 2.0 | 8.0 | 12.0 | Q1 |

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|-------------------|--------------|-----------------|------|------|-------------|------------|-------------|
| TPS92075DDC/NOPB | SOT-23-THIN | DDC | 6 | 1000 | 210.0 | 185.0 | 35.0 |
| TPS92075DDCR/NOPB | SOT-23-THIN | DDC | 6 | 3000 | 210.0 | 185.0 | 35.0 |
| TPS92075DR/NOPB | SOIC | D | 8 | 2500 | 367.0 | 367.0 | 35.0 |

D (R-PDSO-G8)

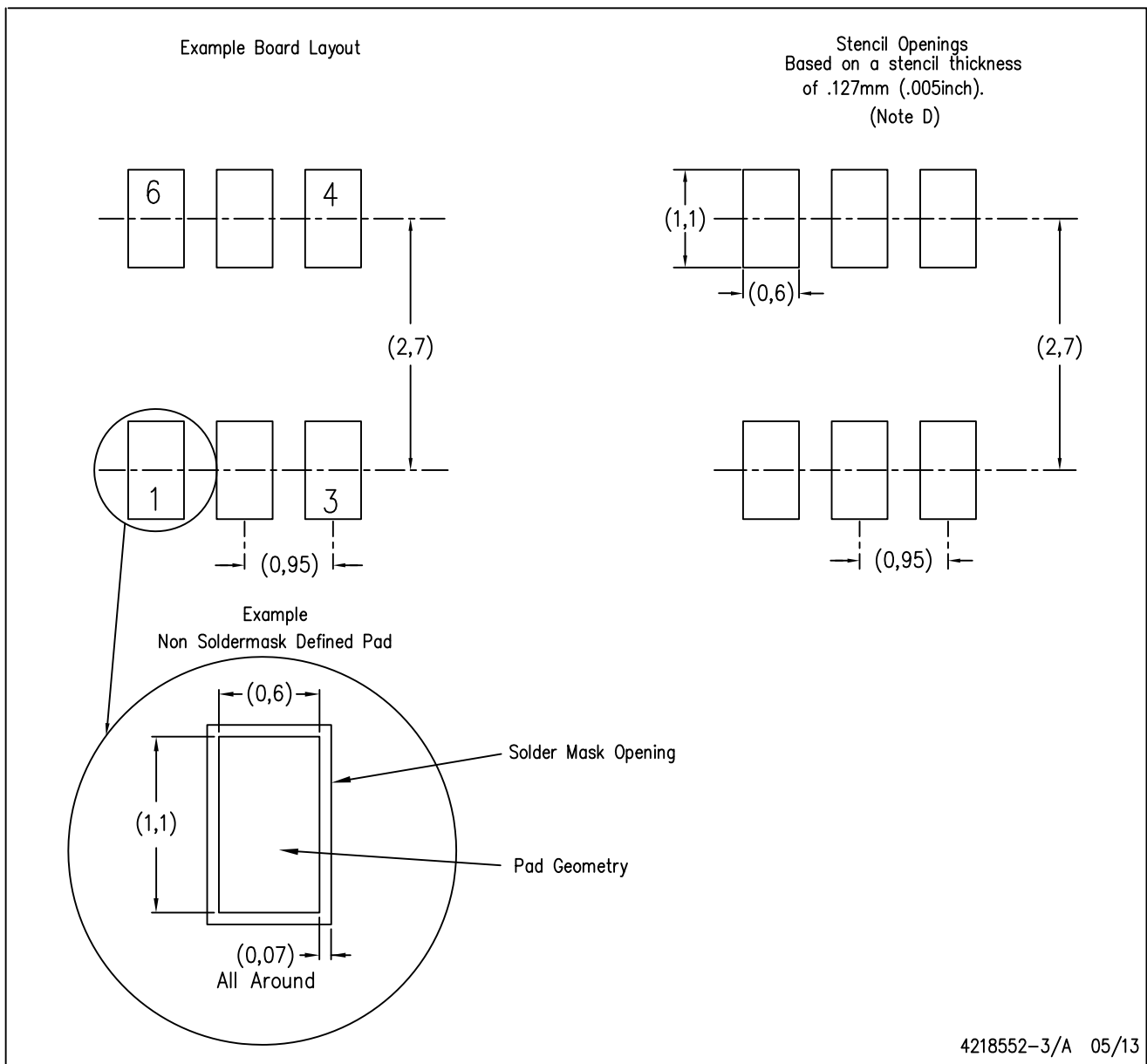
PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 - E. Reference JEDEC MS-012 variation AA.

DDC (R-PDSO-G6)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.

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